

Technical Characteristics

Quality Conformance Inspections	MIL-DTL-55302
Design Criteria	IEC 61076-4-101
Contact Spacing	0.079 [2.00]
Suggested PCB Hole Diameter	0.024 [0.60] ± 0.002 [0.05] after plating

Mechanical & Environmental

Insulation Resistance	> 10,000 MΩ
Low Level Contact Resistance	20 mΩ max
Mating Force	0.17 LBF per mating contact
Contact Life Cycle	200 per mated connector pair
Temperature Rating	-55° C to 125° C
Flammability Rating	UL 94V0
Mechanical Shock	30 G peak value (GR-1217-CORE Telecordia)
Vibration	10-500 Hz @ 10 G (GR-1217-CORE Telecordia)

Materials & Finishes

Insulator	Female housing: PBT UL94 V-0 Male housing: PBT UL94 V-0 Wafer: LCP UL94 V-0
Contact	Copper alloy
Mating Contact Plating	1.27 μm [50 μin] gold min. over 1.27 μm [50 μin] nickel min.
Press Fit PCB Termination	2.50 μm [98 μin] tin min. over 1.27 μm [50 μin] nickel min.

Electrical

Current Rating	1.0 A @ 20°C
Voltage Rating	500 VAC
Dielectric Withstanding Voltage	750V RMS